

CLAIMS

1. An online entrusting system comprises:
 - a processing controller to process an order inputted by a user, wherein said order includes a requiring information;
 - a database coupled to said processing controller to store said requiring information and a schedule information;
 - a plurality of analyzing modules coupled to said processing controller to produce an analysis result about said requiring information being attained or not; and
 - a replying means responding said analysis result of said analyzing modules to said user.
2. The system of claim 1, wherein said user inputs said requiring information via an interface of internet.
3. The system of claim 1, wherein said requiring information includes a substrate type.
4. The system of claim 1, wherein said requiring information includes a die dimension.
5. The system of claim 1, wherein said requiring information includes a package type.
6. The system of claim 1, wherein said requiring information includes the thermal performance.
7. The system of claim 1, wherein said requiring information includes the amount of substrate layers.
8. The system of claim 1, wherein said requiring information includes the number of a plurality of input terminals and a plurality of output terminals.

9. The system of claim 8, wherein said requiring information includes the pitch between said input terminals and output terminals.

10. The system of claim 1, wherein said schedule information includes the information about processing said order and the result for processing said order.

11. The system of claim 1, wherein said plurality of analyzing modules include the thermal analysis module, a circuit analysis module, a stress analysis module, a reliability analysis module, a material analysis module and a substrate analysis module.

12. A method for automatically providing online package entrusting comprises:
inputting an requiring information about a semiconductor package by a user;
storing said requiring information in a database;
producing a plurality of analysis results by a plurality of analysis modules according to said requiring information of said order;
recording said analysis results in said database; and
responding said analysis results to said user by a replying means.

13. The method of claim 12, wherein said user inputs said requiring information via internet.

14. The method of claim 12, wherein said requiring information includes a substrate type.

15. The method of claim 12, wherein said requiring information includes the die dimension.

16. The method of claim 12, wherein said requiring information includes a package type.

17. The method of claim 12, wherein said requiring information includes the thermal performance.

18. The method of claim 12, wherein said requiring information includes the number of a plurality of input terminals and a plurality of output terminals.

19. The method of claim 12, wherein said user receives said analysis results from said replying means by an electronic mail, a facsimile, a short message or all of that input terminals and output terminals

20. The method of claim 12, wherein said plurality of analyzing modules include the thermal analysis module, circuit analysis module, stress analysis module, reliability analysis module, material analysis module and substrate analysis module.